

HT3500, HT5000 Thermally Conductive Gap Fillers

BENEFITS AND FEATURES

- High thermal performance
- low contact resistance
- Easily dispensable and reworkable
- High compressibility for low stress applications
- Reliable thermal performance
- No pump out and cracking risk

OVERVIEW

Honeywell HT one-part series Gap Filler provides an effective thermal properties and high conformability with its high compressibility. It is formulated to deliver high dispense rates for improved productivity, long-term reliability performance and easy reworkability. It is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing, and provide scalable application at a competitive cost.



TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Power supplies & semiconductors
- Memory & power modules
- Power electronics

| Property | HT3500 | HT5000 | Test Method |
|---|----------------|----------------|-------------------------|
| Feature | Silicone-based | Silicone-based | - |
| | Pre-cured | Pre-cured | - |
| Color | Dark red | Grey | Visual |
| Specific Gravity | 3.2 | 3.4 | ASTM D792 |
| Thermal Conductivity (W/m-K) | 3.5 | 5.0 | ASTM D5470 |
| Thermal Impedance (°C-cm ² /W) | <0.35 | <0.25 | ASTM D5470 at BLT |
| Minimum BLT(mm) | 0.10 | 0.05 | - |
| Dispense Rate (g/min) | >10 | >10 | 90Psi, 30cc EFD syringe |
| Out Gassing (TML) | <0.5% | <0.5% | ASTM E595 |
| Storage Condition | RT | RT | - |
| Shelf (month) | 12 | 12 | - |

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